What is claimed is:

(1.) In an assembly in which a plurality of electronic devices of different kinds are connected to a single electronic device, said electronic devices are connected to each other by conductive portions implemented by metal, but insulated from each other by insulating portions implemented by an adhesive, sealable patterned resin layer.

2. An assembly as claimed in claim 1, wherein said resin layer is photoconductive and thermosetting.

3. An assembly as claimed in claim 2, wherein said resin layer is so patterned as to be absent around wiring portions protruding from said electronic devices, around passive devices mounted between said electronic devices, around portions of circuit surfaces of said electronic devices where resin forming said resin layer would effect a device characteristic, around electrode pads, and around bumps formed on said electrode pads.

4. An assembly as claimed in claim 2, wherein said resin layer has a function for flip chip bonding and a function for passivation.

5. An assembly as claimed in claim 4, wherein said resin layer is so patterned as to be absent around wiring portions protruding from said electronic devices, around passive devices mounted between said electronic devices, around portions of circuit surfaces of said electronic devices where resin forming said resin layer would effect a device characteristic, around electrode pads, and around bumps formed on said electrode pads.

6. An assembly as claimed in claim 1, wherein said resin layer

has a function for flip chip bonding and a function for passivation.

7. An assembly as claimed in claim 6, wherein said resin layer is so patterned as to be absent around wiring portions protruding from said electronic devices, around passive devices mounted between said electronic devices, around portions of circuit surfaces of said electronic devices where resin forming said resin layer would effect a device characteristic, around electrode pads, and around bumps formed on said electrode pads.

8. An assembly as claimed in claim 1, wherein said resin layer is so patterned as to be absent around wiring portions protruding from said electronic devices, around passive devices mounted between said electronic devices, around portions of circuit surfaces of said electronic devices where resin forming said resin layer would effect a device characteristic, around electrode pads, and around bumps formed on said electrode pads.

9. In a method of connecting at least two electronic devices included in an assembly in which a plurality of electronic devices of different kinds are connected to a single electronic device, said electronic devices are connected to each other by conductive portions implemented by metal, but insulated from each other by insulating portions implemented by an adhesive, sealable patterned resin layer, said method comprising a step of subjecting said adhesive, sealable resin and electrodes to thermocompression at the same time.

10. In a method of connecting at least two electronic devices included in an assembly in which a plurality of electronic devices

of different kinds are connected to a single electronic device, said electronic devices are connected to each other by conductive portions implemented by metal, but insulated from each other by insulating portions implemented by an adhesive, sealable patterned resin layer, said method comprising a first step of connecting said conductive portions by applying an ultrasonic wave while holding bumps and electrode pads aligned with said bumps in contact with each other, and a second of connecting a resin layer formed on any one of said electronic devices and a contact surface formed on a function element corresponding to said resin layer by thermocompression, said second step being executed after or simultaneously with said first step.

11. In a method of constructing an assembly in which a plurality of electronic devices of different kinds are connected to a single electronic device, said electronic devices are connected to each other by conductive portions implemented by metal, but insulated from each other by insulating portions implemented by an adhesive, sealable and patterned resin layer, said method comprising a step of connecting at least two of said electronic devices via thermosetting, sealable resin layer while maintaining, on a passive device mounted on any one of said electronic devices or on a circuit surface of the electronic device, a temperature of portions where resin constituting said resin layer would effect a device characteristic higher than a temperature of the other portions.